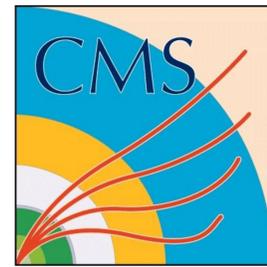
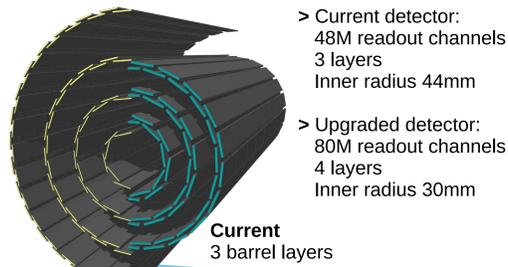


Test Beam Campaigns for the CMS Phase I Upgrade Pixel Readout-Chip.

Simon Spannagel for the DESY CMS Pixel Detector Group
10th International Conference on Position Sensitive Detectors, 7-12/9/2014

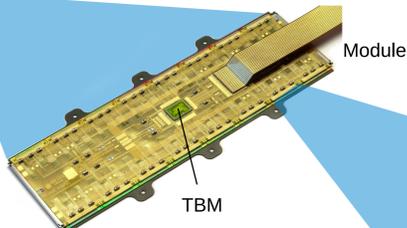


CMS Barrel Pixel Detector



Upgrade
4 barrel layers

Current
3 barrel layers



- > Pixel detector built of modules
- > Each module comprises 16 Read-out chips (ROCs) on one Si sensor
- > Programming and data transfer managed by the Token-Bit Manager (TBM) chip

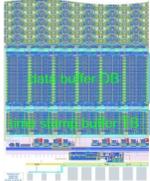
Data Loss Predictions

Detector & Layer	Data loss for different luminosities		
	1x10 ³⁴ cm ⁻² s ⁻¹ 25ns BX	2x10 ³⁴ cm ⁻² s ⁻¹ 25ns BX	2x10 ³⁴ cm ⁻² s ⁻¹ 50ns BX
Current L1	4.0%	16.0%	50.0%
Current L2	1.5%	5.8%	18.2%
Upgraded L1	1.19%	2.38%	4.76%
Upgraded L2	0.23%	0.46%	0.93%

Digital 160MHz Readout & additional on-Chip Buffers

- > Fully-digital 160 MHz readout for higher bandwidth
- > Replaces analog level-based 40 MHz approach
- > fast on-chip 8-bit ADC for pulse-height sampling

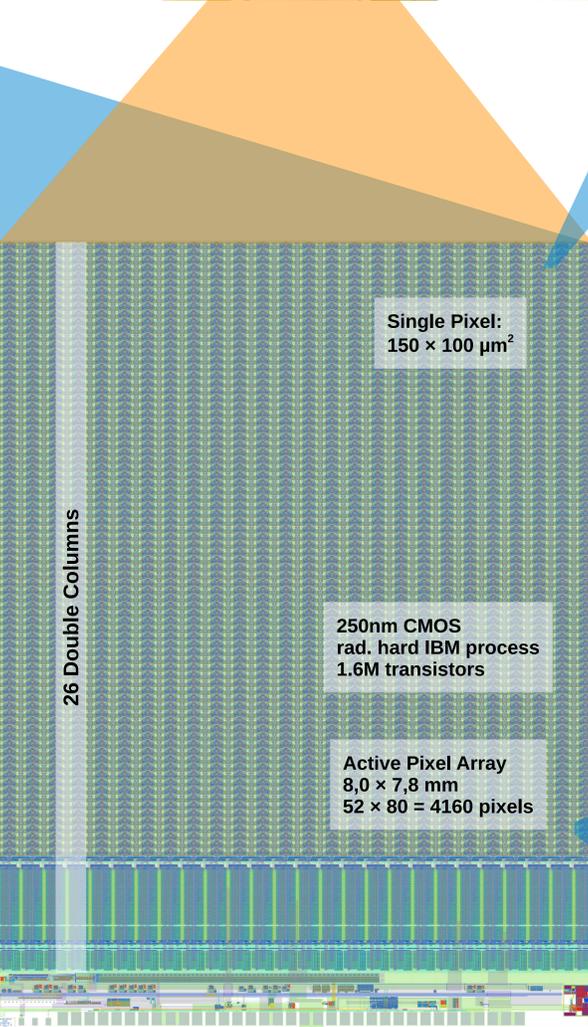
analog PSI46



Additional buffer cells

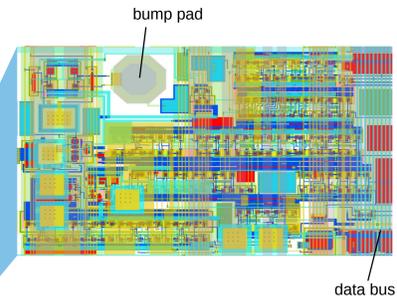
- > Data buffers: 32 cells to 80 cells
- > Time stamp buffers: 12 cells to 24 cells
- > Reduced buffer cell size to stay compatible with old design
- > Reduced dead time during readout by additional global readout buffer

The CMS Pixel Readout-Chip



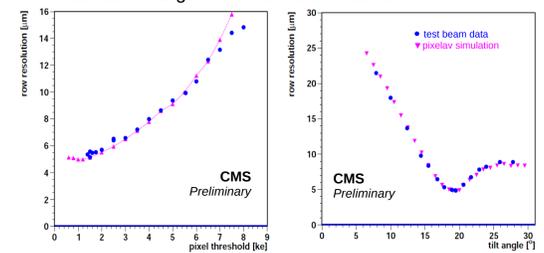
Pixel Unit Cell

- > Smallest logic unit of the Readout-Chip, 256 transistors
- > Contains preamplifier, shaper and comparator for zero-suppressed pulse readout
- > Organized in Double Columns for data readout

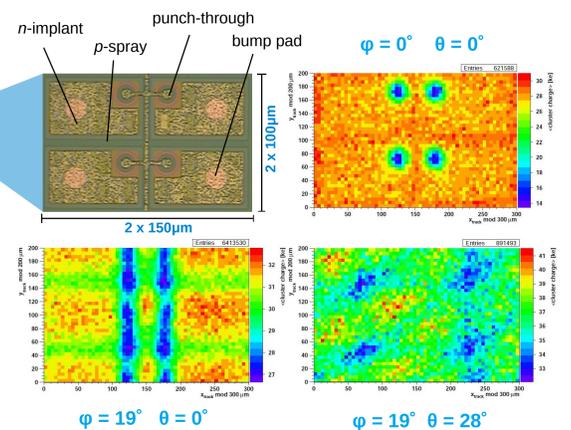


Low Threshold, High Position Resolution

- > In-time threshold (assigned to correct trigger window)
Current ROC: ~3,500 e
New ROC: <1,800 e
- > Reduced internal cross-talk from power rails
- > Increased comparator speed
- > Reduced threshold allows better position resolution
- > Also increases detector longevity, compensating for reduced charge collection after irradiation

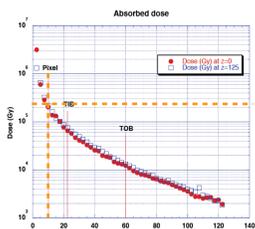


Detailed ROC/Sensor Studies



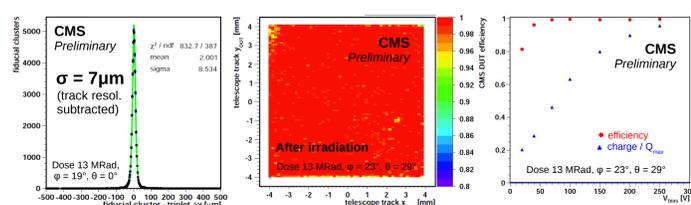
Performance of Irradiated Devices

- > Irradiation: 24 GeV protons
- > Two devices, doses up to D = 13 Mrad
Φ ≈ 2.3 × 10¹⁴ n_{eq} / cm²
- > Expected lifetime dose 500fb⁻¹ of Layers 4
- > Tracking and charge collection studied in the DESY test beam



After irradiation:

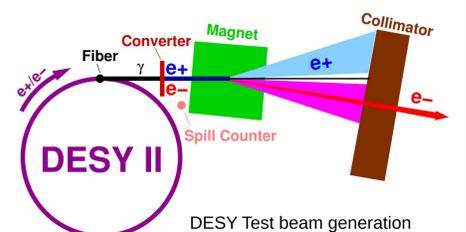
- > Only partially depleted sensor (limits on power dissipation)
- > n-in-n implant concept as the sensor undergoes type inversion
- > Depletion and charge collected at implant side
- > High resolution, tracking efficiency and charge collection maintained



DESY Testbeam & DATURA Telescope

- > Beam generation via bremsstrahlung and pair production
- > Energies selectable from 1-6 GeV
- > (Instantaneous) particle rates in the Hz – few kHz range
- > Energy spread of 5%
- > Beam Divergence ~1mrad

- > Test beam equipped with beam telescopes
- > Developed at DESY for test beams worldwide
- > High-precision tracking, low material budget
- > Six MIMOSA26 MAPS, 18.4 μm pitch, 50 μm thickness, 120 μs integration window
- > Mechanical Support, cooling, Trigger Logic Unit (TLU), four-fold coincidence trigger
- > Full-featured Data Acquisition (DAQ) and analysis system (EUDAQ, EU Telescope)



contact:



simon.spannagel@desy.de

efficiency map of the DUT

